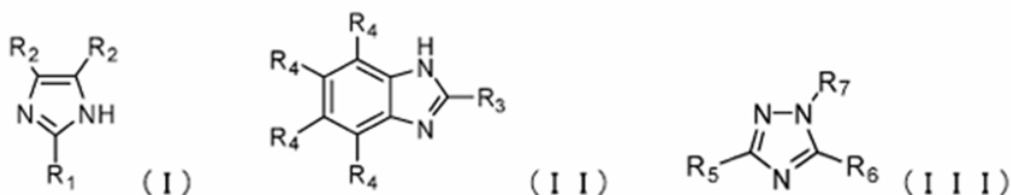


ABSTRACT

SURFACE TREATMENT AGENT FOR COPPER OR COPPER ALLOY

5 The present invention addresses the problem of providing a surface treatment agent that exhibits excellent heat resistance of a chemical conversion film formed on a copper surface and ensures good solderability during soldering. A surface treatment agent for copper or copper alloy according to the present invention contains: an imidazole compound represented by chemical formula (I) or a benzimidazole compound represented by chemical formula (II); and a triazole compound represented by chemical formula (III). The definition of
10 each substituent in chemical formulae (I)-(III) is the same as that defined in the specification.

[Chem. 1]



No Figure